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### **Understanding Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### **Details**

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6000
Total RAM Bits	73728
Number of I/O	100
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp6c-5tn144c">https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp6c-5tn144c</a>

**Slice**

Each slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-3 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge/level clocks.

There are 14 input signals: 13 signals from routing and one from the carry-chain (from adjacent slice or PFU). There are 7 outputs: 6 to routing and one to carry-chain (to adjacent PFU). Table 2-1 lists the signals associated with each slice.

**Figure 2-3. Slice Diagram**

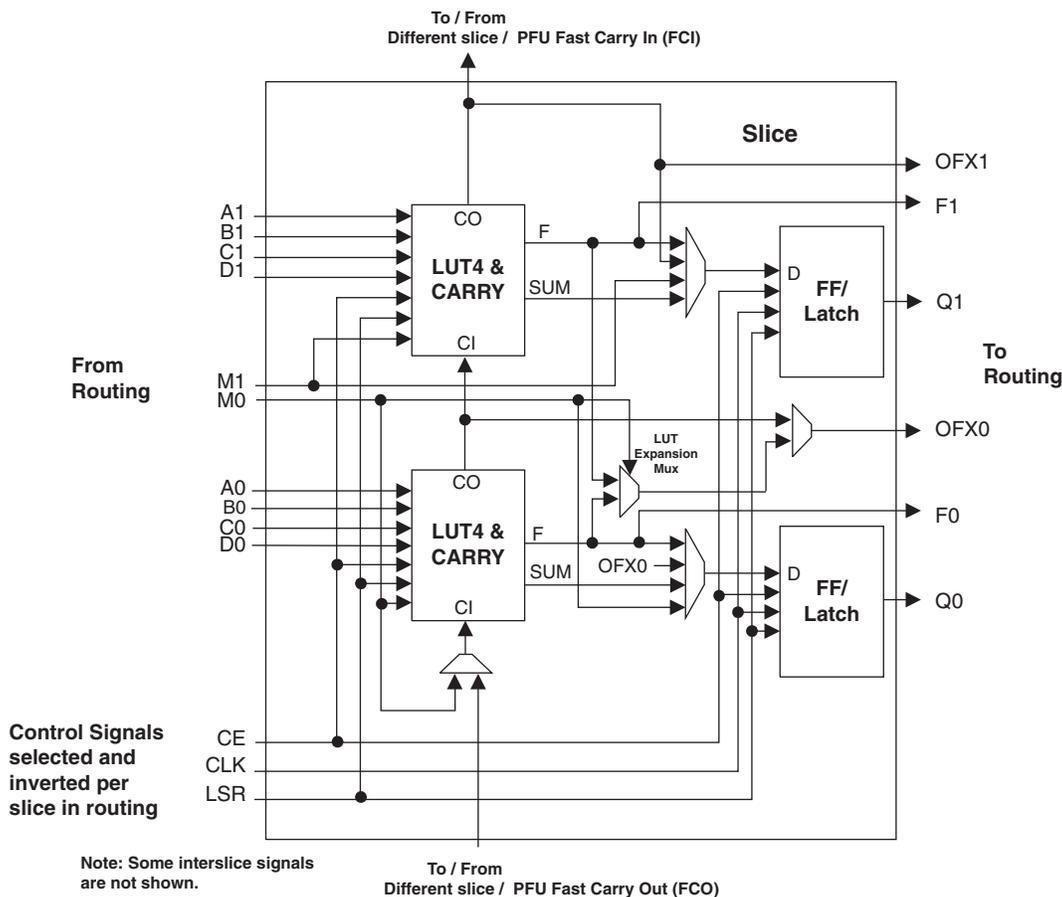
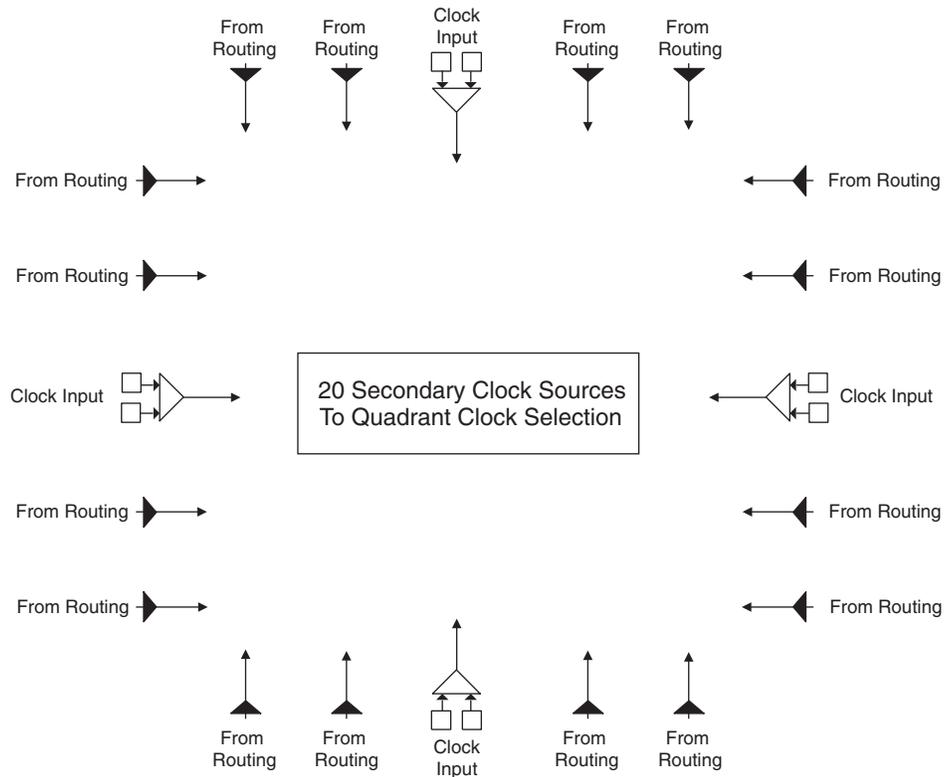


Figure 2-6. Secondary Clock Sources



### Clock Routing

The clock routing structure in LatticeXP devices consists of four Primary Clock lines and a Secondary Clock network per quadrant. The primary clocks are generated from MUXs located in each quadrant. Figure 2-7 shows this clock routing. The four secondary clocks are generated from MUXs located in each quadrant as shown in Figure 2-8. Each slice derives its clock from the primary clock lines, secondary clock lines and routing as shown in Figure 2-9.

Figure 2-7. Per Quadrant Primary Clock Selection

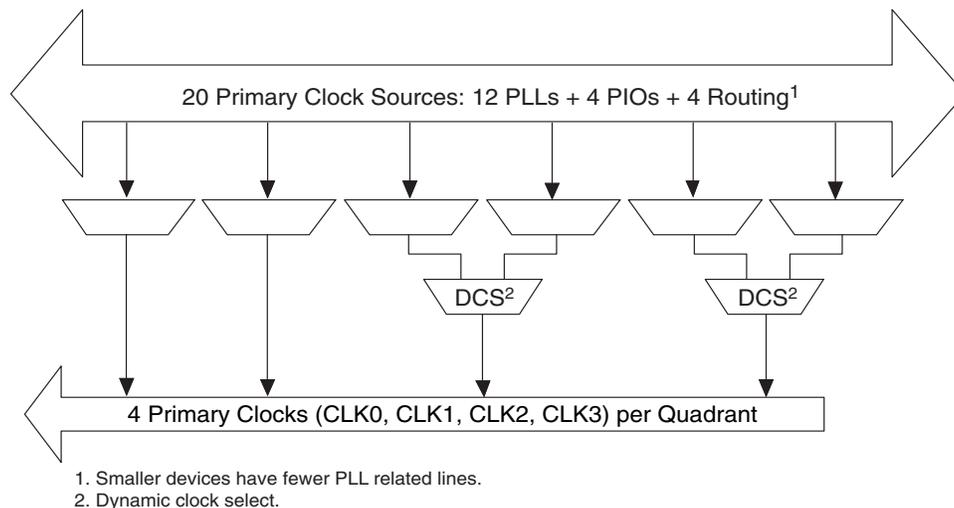
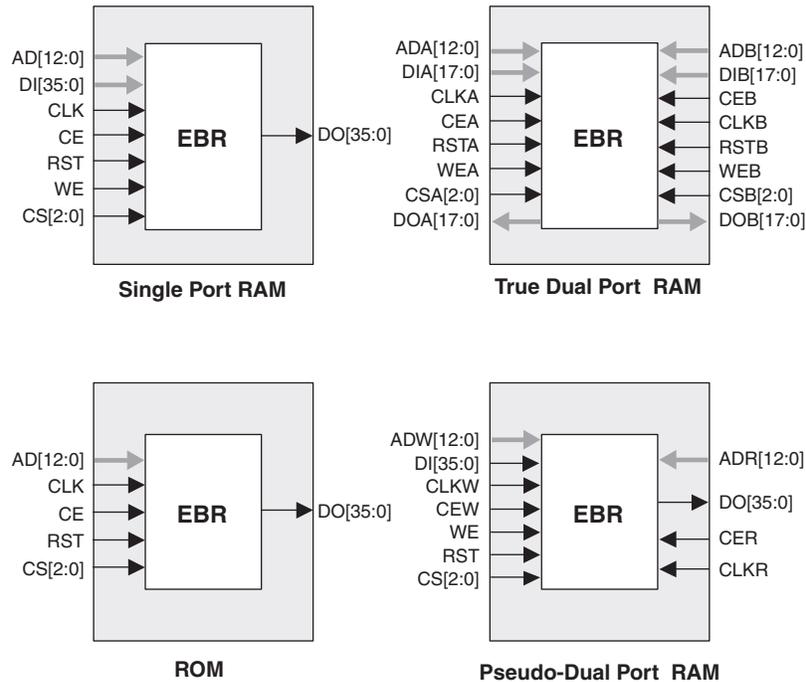


Figure 2-14. sysMEM Memory Primitives



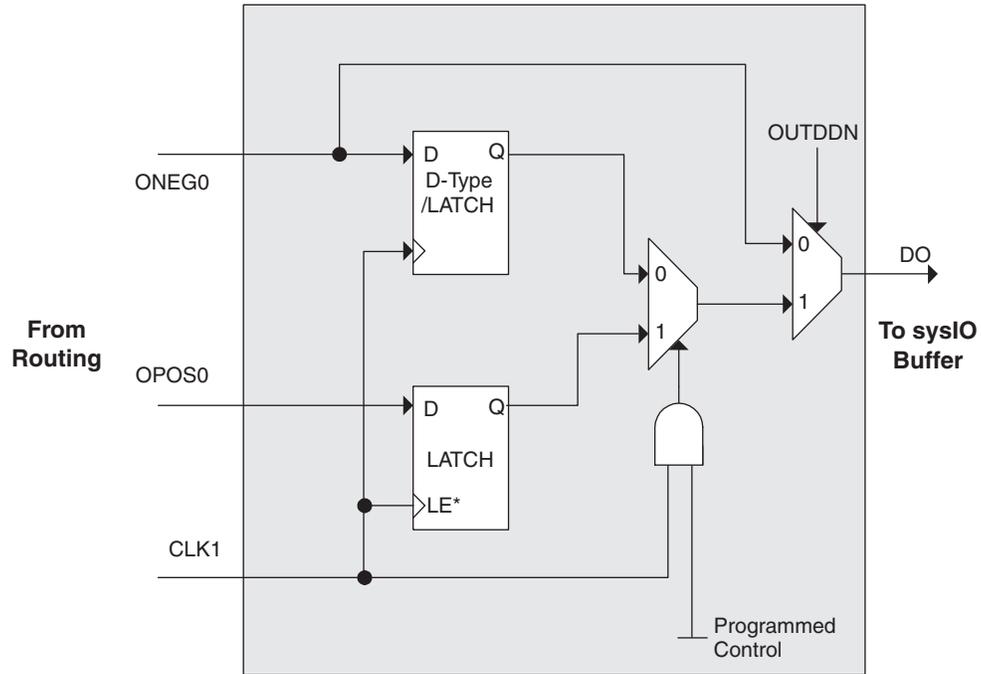
The EBR memory supports three forms of write behavior for single port or dual port operation:

1. **Normal** – data on the output appears only during read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.
2. **Write Through** - a copy of the input data appears at the output of the same port during a write cycle. This mode is supported for all data widths.
3. **Read-Before-Write** – when new data is being written, the old content of the address appears at the output. This mode is supported for x9, x18 and x36 data widths.

### Memory Core Reset

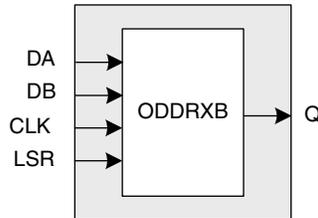
The memory array in the EBR utilizes latches at the A and B output ports. These latches can be reset asynchronously. RSTA and RSTB are local signals, which reset the output latches associated with Port A and Port B respectively. The Global Reset (GSRN) signal resets both ports. The output data latches and associated resets for both ports are as shown in Figure 2-15.

Figure 2-23. Output Register Block



\*Latch is transparent when input is low.

Figure 2-24. ODDRXB Primitive

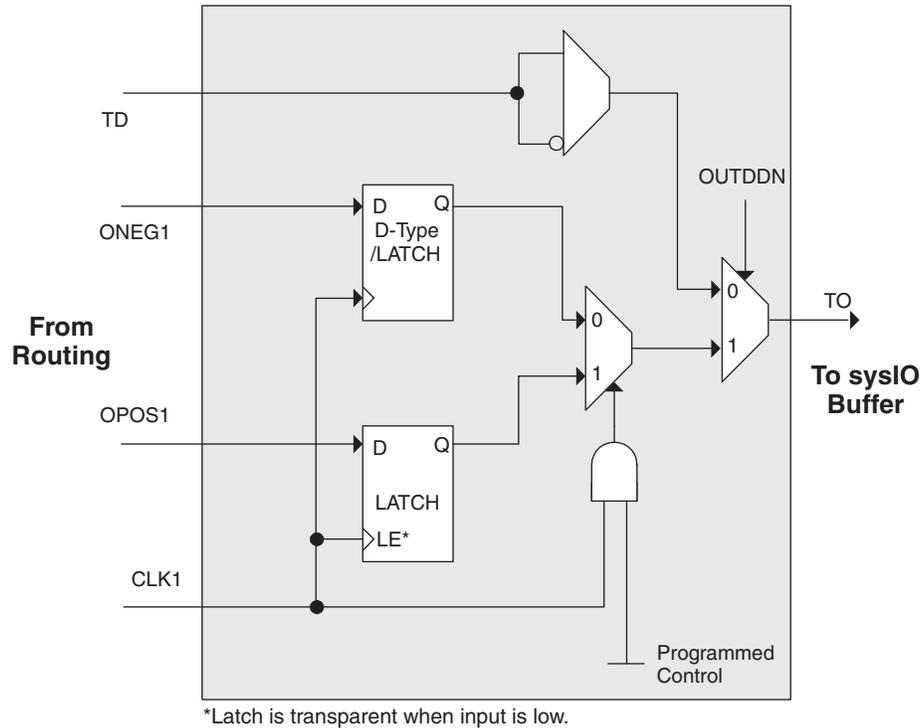


**Tristate Register Block**

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-25 shows the diagram of the Tristate Register Block.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 is fed into one register on the positive edge of the clock and OPOS1 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-25. Tristate Register Block



**Control Logic Block**

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing and a DQS signal provided from the programmable DQS pin. The clock can optionally be inverted.

The clock enable and local reset signals are selected from the routing and optionally inverted. The global tristate signal is passed through this block.

**DDR Memory Support**

Implementing high performance DDR memory interfaces requires dedicated DDR register structures in the input (for read operations) and in the output (for write operations). As indicated in the PIO Logic section, the LatticeXP devices provide this capability. In addition to these registers, the LatticeXP devices contain two elements to simplify the design of input structures for read operations: the DQS delay block and polarity control logic.

**DLL Calibrated DQS Delay Block**

Source Synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment, however in DDR memories the clock (referred to as DQS) is not free running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds the polarity control logic which controls the polarity of the clock to the sync registers in the input register blocks. Figures 2-26 and 2-27 show how the polarity control logic are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two DLLs on opposite sides of the device. Each DLL compensates DQS Delays in its half of the device as shown in Figure 2-27. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

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## Polarity Control Logic

In a typical DDR Memory interface design, the phase relation between the incoming delayed DQS strobe and the internal system Clock (during the READ cycle) is unknown.

The LatticeXP family contains dedicated circuits to transfer data between these domains. To prevent setup and hold violations at the domain transfer between DQS (delayed) and the system Clock a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of the each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects this transition. This signal is used to control the polarity of the clock to the synchronizing registers.

## sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in eight groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

### sysIO Buffer Banks

LatticeXP devices have eight sysIO buffer banks; each is capable of supporting multiple I/O standards. Each sysIO bank has its own I/O supply voltage ( $V_{CCIO}$ ), and two voltage references  $V_{REF1}$  and  $V_{REF2}$  resources allowing each bank to be completely independent from each other. Figure 2-28 shows the eight banks and their associated supplies.

In the LatticeXP devices, single-ended output buffers and ratioed input buffers (LVTTTL, LVCMOS, PCI and PCI-X) are powered using  $V_{CCIO}$ . LVTTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as a fixed threshold input independent of  $V_{CCIO}$ . In addition to the bank  $V_{CCIO}$  supplies, the LatticeXP devices have a  $V_{CC}$  core logic power supply, and a  $V_{CCAUX}$  supply that power all differential and referenced buffers.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeXP devices, a dedicated pin in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

**Typical I/O Behavior During Power-up**

The internal power-on-reset (POR) signal is deactivated when  $V_{CC}$  and  $V_{CCAUX}$  have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user's responsibility to ensure that all other  $V_{CCIO}$  banks are active with valid input logic levels to properly control the output logic states of all the I/O banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to  $V_{CCIO}$ . The I/O pins will not take on the user configuration until  $V_{CC}$ ,  $V_{CCAUX}$  and  $V_{CCIO}$  have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The  $V_{CC}$  and  $V_{CCAUX}$  supply the power to the FPGA core fabric, whereas the  $V_{CCIO}$  supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, it is recommended that the I/O buffers be powered-up prior to the FPGA core fabric.  $V_{CCIO}$  supplies should be powered up before or together with the  $V_{CC}$  and  $V_{CCAUX}$  supplies.

**Supported Standards**

The LatticeXP sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTTL and other standards. The buffers support the LVTTTL, LVCMOS 1.2, 1.5, 1.8, 2.5 and 3.3V standards. In the LVCMOS and LVTTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL and HSTL. Differential standards supported include LVDS, BLVDS, LVPECL, differential SSTL and differential HSTL. Tables 2-7 and 2-8 show the I/O standards (together with their supply and reference voltages) supported by the LatticeXP devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

**Table 2-7. Supported Input Standards**

Input Standard	$V_{REF}$ (Nom.)	$V_{CCIO}^1$ (Nom.)
<b>Single Ended Interfaces</b>		
LVTTTL	—	—
LVCMOS33 <sup>2</sup>	—	—
LVCMOS25 <sup>2</sup>	—	—
LVCMOS18	—	1.8
LVCMOS15	—	1.5
LVCMOS12 <sup>2</sup>	—	—
PCI	—	3.3
HSTL18 Class I, II	0.9	—
HSTL18 Class III	1.08	—
HSTL15 Class I	0.75	—
HSTL15 Class III	0.9	—
SSTL3 Class I, II	1.5	—
SSTL2 Class I, II	1.25	—
SSTL18 Class I	0.9	—
<b>Differential Interfaces</b>		
Differential SSTL18 Class I	—	—
Differential SSTL2 Class I, II	—	—
Differential SSTL3 Class I, II	—	—
Differential HSTL15 Class I, III	—	—
Differential HSTL18 Class I, II, III	—	—
LVDS, LVPECL	—	—
BLVDS	—	—

1. When not specified  $V_{CCIO}$  can be set anywhere in the valid operating range.

2. JTAG inputs do not have a fixed threshold option and always follow  $V_{CCJ}$ .

**Programming and Erase Flash Supply Current<sup>1, 2, 3, 4, 5</sup>**

Symbol	Parameter	Device	Typ <sup>6</sup>	Units
I <sub>CC</sub>	Core Power Supply	LFXP3E	30	mA
		LFXP6E	40	mA
		LFXP10E	50	mA
		LFXP15E	60	mA
		LFXP20E	70	mA
		LFXP3C	50	mA
		LFXP6C	60	mA
		LFXP10C	90	mA
		LFXP15C	100	mA
		LFXP20C	110	mA
I <sub>CCAUX</sub>	Auxiliary Power Supply V <sub>CCAUX</sub> = 3.3V	LFXP3E/C	50	mA
		LFXP6E/C	60	mA
		LFXP10E/C	90	mA
		LFXP15E/C	110	mA
		LFXP20E/C	130	mA
I <sub>CCJ</sub>	V <sub>CCJ</sub> Power Supply <sup>7</sup>	All	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V<sub>CCIO</sub> or GND.
3. Blank user pattern; typical Flash pattern.
4. Bypass or decoupling capacitor across the supply.
5. JTAG programming is at 1MHz.
6. T<sub>A</sub>=25°C, power supplies at nominal voltage.
7. When programming via JTAG.

## Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

## LVDS25E

The top and bottom side of LatticeXP devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

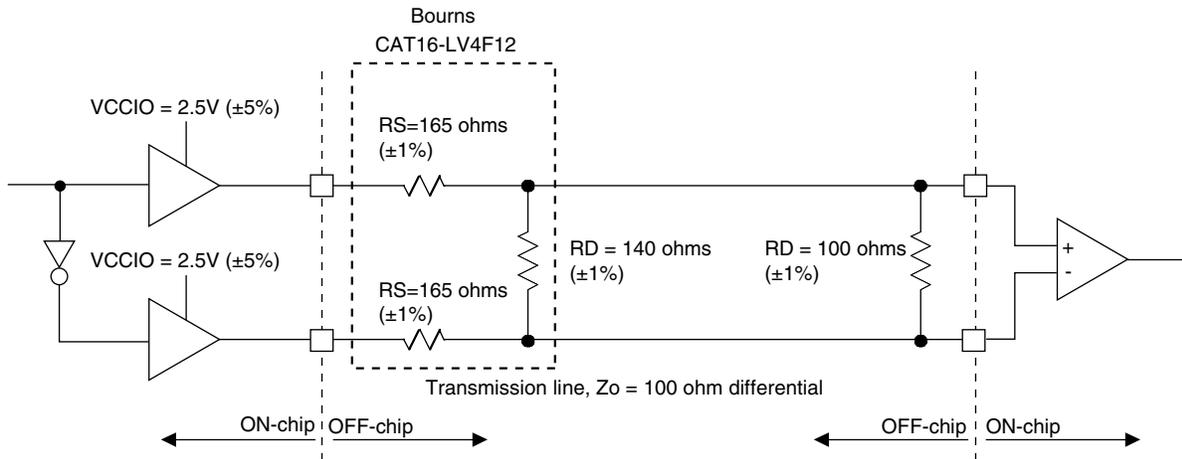


Table 3-1. LVDS25E DC Conditions

### Over Recommended Operating Conditions

Parameter	Description	Typical	Units
$V_{OH}$	Output high voltage	1.43	V
$V_{OL}$	Output low voltage	1.07	V
$V_{OD}$	Output differential voltage	0.35	V
$V_{CM}$	Output common mode voltage	1.25	V
$Z_{BACK}$	Back impedance	100	ohms
$I_{DC}$	DC output current	3.66	mA

## BLVDS

The LatticeXP devices support BLVDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Figure 3-2. BLVDS Multi-point Output Example

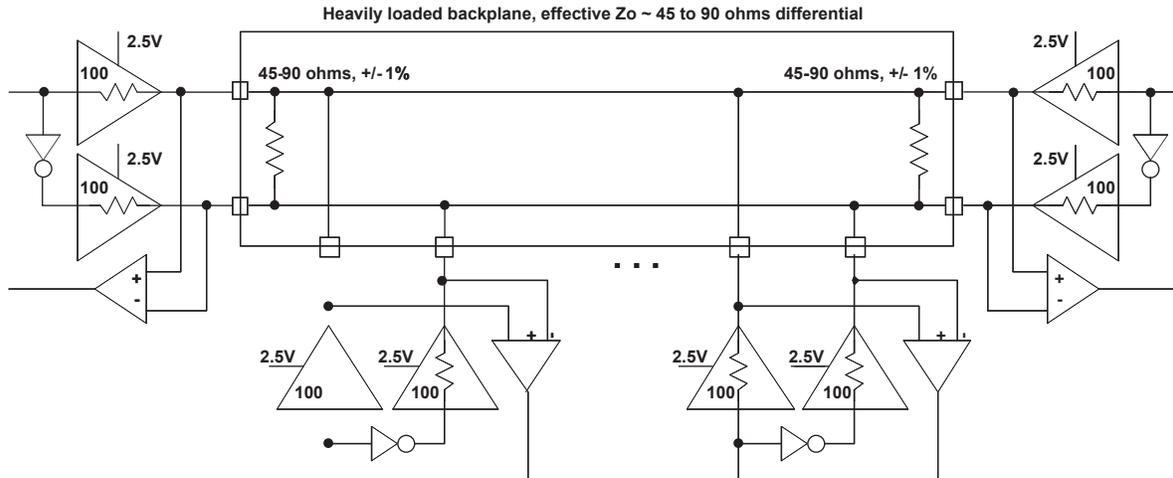


Table 3-2. BLVDS DC Conditions<sup>1</sup>

Over Recommended Operating Conditions

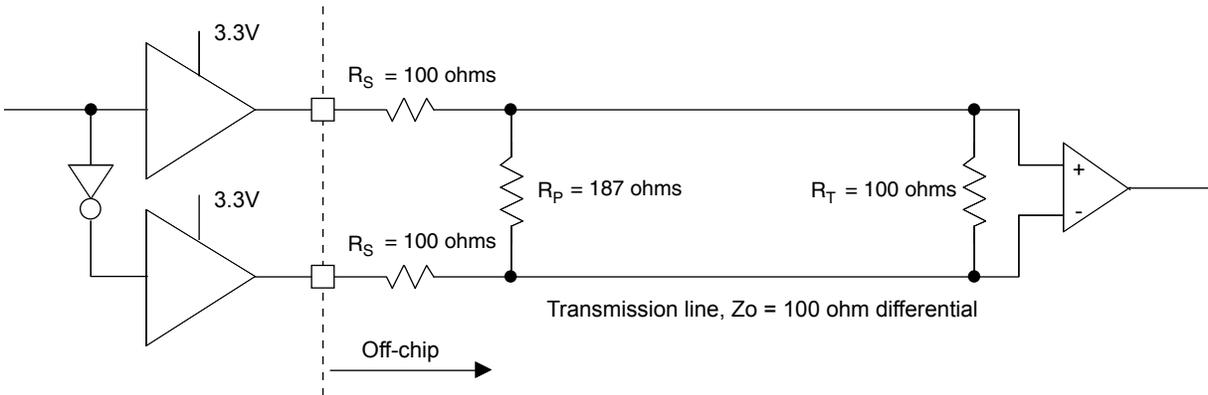
Symbol	Description	Typical		Units
		Zo = 45	Zo = 90	
Z <sub>OUT</sub>	Output impedance	100	100	ohms
R <sub>TLEFT</sub>	Left end termination	45	90	ohms
R <sub>TRIGHT</sub>	Right end termination	45	90	ohms
V <sub>OH</sub>	Output high voltage	1.375	1.48	V
V <sub>OL</sub>	Output low voltage	1.125	1.02	V
V <sub>OD</sub>	Output differential voltage	0.25	0.46	V
V <sub>CM</sub>	Output common mode voltage	1.25	1.25	V
I <sub>DC</sub>	DC output current	11.2	10.2	mA

1. For input buffer, see LVDS table.

**LVPECL**

The LatticeXP devices support differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

**Figure 3-3. Differential LVPECL**



**Table 3-3. LVPECL DC Conditions<sup>1</sup>**

**Over Recommended Operating Conditions**

Symbol	Description	Typical	Units
Z <sub>OUT</sub>	Output impedance	100	ohms
R <sub>P</sub>	Driver parallel resistor	187	ohms
R <sub>S</sub>	Driver series resistor	100	ohms
R <sub>T</sub>	Receiver termination	100	ohms
V <sub>OH</sub>	Output high voltage	2.03	V
V <sub>OL</sub>	Output low voltage	1.27	V
V <sub>OD</sub>	Output differential voltage	0.76	V
V <sub>CM</sub>	Output common mode voltage	1.65	V
Z <sub>BACK</sub>	Back impedance	85.7	ohms
I <sub>DC</sub>	DC output current	12.7	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

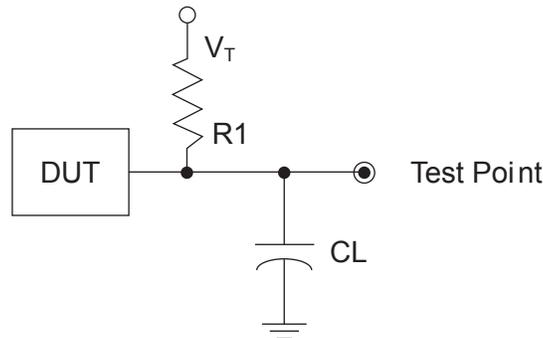
**RSDS**

The LatticeXP devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

### Switching Test Conditions

Figure 3-13 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

**Figure 3-13. Output Test Load, LVTTTL and LVCMOS Standards**



**Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces**

Test Condition	R <sub>1</sub>	C <sub>L</sub>	Timing Ref.	V <sub>T</sub>
LVTTTL and other LVCMOS settings (L -> H, H -> L)	∞	0pF	LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = V <sub>CCIO</sub> /2	—
			LVCMOS 1.8 = V <sub>CCIO</sub> /2	—
			LVCMOS 1.5 = V <sub>CCIO</sub> /2	—
			LVCMOS 1.2 = V <sub>CCIO</sub> /2	—
LVCMOS 2.5 I/O (Z -> H)	188	0pF	V <sub>CCIO</sub> /2	V <sub>OL</sub>
LVCMOS 2.5 I/O (Z -> L)			V <sub>CCIO</sub> /2	V <sub>OH</sub>
LVCMOS 2.5 I/O (H -> Z)			V <sub>OH</sub> - 0.15	V <sub>OL</sub>
LVCMOS 2.5 I/O (L -> Z)			V <sub>OL</sub> + 0.15	V <sub>OH</sub>

Note: Output test conditions for all other interfaces are determined by the respective standards.

**Signal Descriptions (Cont.)**

Signal Name	I/O	Descriptions
<b>Test and Programming</b> (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
V <sub>CCJ</sub>	—	V <sub>CCJ</sub> - The power supply pin for JTAG Test Access Port.
<b>Configuration Pads</b> (used during sysCONFIG)		
CFG[1:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. If CFG1 and CFG0 are high (SDM) then this pin is pulled low.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY	I/O	Generally not used. After configuration it is a user-programmable I/O pin.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled. After configuration it is user a programmable I/O pin.
CS1N	I	sysCONFIG chip select (Active Low). During configuration, a pull-up is enabled. After configuration it is user programmable I/O pin
WRITEN	I	Write Data on Parallel port (Active low). After configuration it is a user programmable I/O pin
D[7:0]	I/O	sysCONFIG Port Data I/O. After configuration these are user programmable I/O pins.
DOUT, CSON	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port. After configuration, it is a user-programmable I/O pin.
DI	I	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. After configuration it is a user-programmable I/O pin.
SLEEPN <sup>2</sup>	I	Sleep Mode pin - Active low sleep pin. p When this pin is held high, the device operates normally. p When driven low, the device moves into Sleep Mode after a specified time. This pin has a weak internal pull-up, but when not used an external pull-up to V <sub>CC</sub> is recommended.
TOE <sup>3</sup>	I	Test Output Enable tri-states all I/O pins when driven low. This pin has a weak internal pull-up, but when not used an external pull-up to V <sub>CC</sub> is recommended.

1. Applies to LFXP10, LFXP15 and LFXP20 only.

2. Applies to LFXP "C" devices only.

3. Applies to LFXP "E" devices only.

**LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)**

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
K4	PL20A	6	T	-	PL29A	6	T	-
K5	PL20B	6	C	-	PL29B	6	C	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
N1	PL23B	6	-	VREF2_6	PL31A	6	-	VREF2_6
N2	PL21B	6	C <sup>3</sup>	-	PL32B	6	-	-
P1	PL24A	6	T <sup>3</sup>	DQS	PL33A	6	T <sup>3</sup>	DQS
P2	PL24B	6	C <sup>3</sup>	-	PL33B	6	C <sup>3</sup>	-
L5	PL25A	6	T	-	PL34A	6	T	LLM0_PLLT_FB_A
M6	PL25B	6	C	-	PL34B	6	C	LLM0_PLLC_FB_A
M3	PL26A	6	T <sup>3</sup>	-	PL35A	6	T <sup>3</sup>	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
N3	PL26B	6	C <sup>3</sup>	-	PL35B	6	C <sup>3</sup>	-
P4	SLEEPN <sup>1</sup> /TOE <sup>2</sup>	-	-	-	SLEEPN <sup>1</sup> /TOE <sup>2</sup>	-	-	-
P3	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R4	PB2A	5	T	-	PB6A	5	T	-
N5	PB2B	5	C	-	PB6B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
P5	PB5B	5	-	VREF1_5	PB7A	5	T	VREF1_5
R1	PB3B	5	C	-	PB7B	5	C	-
N6	PB4A	5	-	-	PB8A	5	-	-
M7	PB3A	5	T	-	PB9B	5	-	-
R2	PB6A	5	T	DQS	PB10A	5	T	DQS
T2	PB6B	5	C	-	PB10B	5	C	-
R3	PB7A	5	T	-	PB11A	5	T	-
T3	PB7B	5	C	-	PB11B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
T4	PB8A	5	T	-	PB12A	5	T	-
R5	PB8B	5	C	VREF2_5	PB12B	5	C	VREF2_5
N7	PB9A	5	T	-	PB13A	5	T	-
M8	PB9B	5	C	-	PB13B	5	C	-
T5	PB10A	5	T	-	PB14A	5	T	-
P6	PB10B	5	C	-	PB14B	5	C	-
T6	PB11A	5	T	-	PB15A	5	T	-
R6	PB11B	5	C	-	PB15B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
P7	PB12A	5	-	-	PB16A	5	-	-
N8	PB13B	5	-	-	PB17B	5	-	-
R7	PB14A	5	T	DQS	PB18A	5	T	DQS
T7	PB14B	5	C	-	PB18B	5	C	-
P8	PB15A	5	T	-	PB19A	5	T	-
T8	PB15B	5	C	-	PB19B	5	C	-

**LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)**

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L15	PR21B	3	C <sup>3</sup>	-	PR28B	3	C <sup>3</sup>	-
L14	PR21A	3	T <sup>3</sup>	-	PR28A	3	T <sup>3</sup>	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
L12	PR17B	3	C	-	PR26A	3	-	-
M16	PR20B	3	C	-	PR25B	3	C	RLM0_PLLC_IN_A
N16	PR20A	3	T	-	PR25A	3	T	RLM0_PLLT_IN_A
K14	PR19B	3	C <sup>3</sup>	-	PR24B	3	C <sup>3</sup>	-
K15	PR19A	3	T <sup>3</sup>	-	PR24A	3	T <sup>3</sup>	DQS
K12	PR17A	3	T	-	PR23B	3	-	-
K13	PR22A	3	-	VREF2_3	PR22A	3	-	VREF2_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
L16	PR18B	3	C <sup>3</sup>	-	PR21B	3	C <sup>3</sup>	-
K16	PR18A	3	T <sup>3</sup>	-	PR21A	3	T <sup>3</sup>	-
J15	PR16B	3	C <sup>3</sup>	-	PR19B	3	C <sup>3</sup>	-
J14	PR16A	3	T <sup>3</sup>	-	PR19A	3	T <sup>3</sup>	-
J13	GNDP1	-	-	-	GNDP1	-	-	-
J12	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J16	PR12B	2	C	PCLKC2_0	PR17B	2	C	PCLKC2_0
H16	PR12A	2	T	PCLKT2_0	PR17A	2	T	PCLKT2_0
H13	PR13B	2	C <sup>3</sup>	-	PR16B	2	C <sup>3</sup>	-
H12	PR13A	2	T <sup>3</sup>	-	PR16A	2	T <sup>3</sup>	DQS
H15	PR2B	2	C <sup>3</sup>	-	PR15B	2	-	-
H14	PR6B	2	-	VREF1_2	PR14A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G15	PR11B	2	C <sup>3</sup>	-	PR13B	2	C <sup>3</sup>	-
G14	PR11A	2	T <sup>3</sup>	-	PR13A	2	T <sup>3</sup>	-
G16	PR8B	2	C	RUM0_PLLC_IN_A	PR12B	2	C	RUM0_PLLC_IN_A
F16	PR8A	2	T	RUM0_PLLT_IN_A	PR12A	2	T	RUM0_PLLT_IN_A
G13	PR2A	2	T <sup>3</sup>	-	PR11B	2	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G12	PR9B	2	C <sup>3</sup>	-	PR8B	2	C	-
F13	PR9A	2	T <sup>3</sup>	-	PR8A	2	T	-
B16	PR7B	2	C <sup>3</sup>	-	PR7B	2	C <sup>3</sup>	-
C16	PR7A	2	T <sup>3</sup>	DQS	PR7A	2	T <sup>3</sup>	DQS
F15	PR14A	2	-	-	PR6B	2	-	-
E15	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F14	PR4B	2	C <sup>3</sup>	-	PR4B	2	C <sup>3</sup>	-
E14	PR4A	2	T <sup>3</sup>	-	PR4A	2	T <sup>3</sup>	-
D15	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
C15	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A

**LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)**

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
B3	PT8B	0	C	-	PT12B	0	C	-
A3	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
D7	PT7B	0	C	-	PT11B	0	C	-
C7	PT7A	0	T	DQS	PT11A	0	T	DQS
B2	PT6B	0	-	-	PT10B	0	-	-
C2	PT5A	0	-	-	PT9A	0	-	-
C3	PT4B	0	C	-	PT8B	0	C	-
D3	PT4A	0	T	-	PT8A	0	T	-
F7	PT3B	0	C	-	PT7B	0	C	-
E7	PT3A	0	T	-	PT7A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
C6	-	-	-	-	PT6B	0	C	-
D6	-	-	-	-	PT6A	0	T	-
C5	-	-	-	-	PT5B	0	C	-
C4	-	-	-	-	PT5A	0	T	-
F6	-	-	-	-	PT4B	0	C	-
E6	-	-	-	-	PT4A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-
E4	-	-	-	-	PT3B	0	-	-
E5	CFG0	0	-	-	CFG0	0	-	-
D4	CFG1	0	-	-	CFG1	0	-	-
D5	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-
A2	GND	-	-	-	GND	-	-	-
A21	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-
AA1	GND	-	-	-	GND	-	-	-
AA22	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-
AB2	GND	-	-	-	GND	-	-	-
AB21	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-
B1	GND	-	-	-	GND	-	-	-
B22	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-

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## Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

### For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at [www.latticesemi.com](http://www.latticesemi.com).

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from [www.latticesemi.com/software](http://www.latticesemi.com/software)

**Conventional Packaging****Commercial**

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208C	136	1.8/2.5/3.3V	-3	PQFP	208	COM	3.1K
LFXP3C-4Q208C	136	1.8/2.5/3.3V	-4	PQFP	208	COM	3.1K
LFXP3C-5Q208C	136	1.8/2.5/3.3V	-5	PQFP	208	COM	3.1K
LFXP3C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	3.1K
LFXP3C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	3.1K
LFXP3C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	3.1K
LFXP3C-3T100C	62	1.8/2.5/3.3V	-3	TQFP	100	COM	3.1K
LFXP3C-4T100C	62	1.8/2.5/3.3V	-4	TQFP	100	COM	3.1K
LFXP3C-5T100C	62	1.8/2.5/3.3V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	5.8K
LFXP6C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	5.8K
LFXP6C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	5.8K
LFXP6C-3Q208C	142	1.8/2.5/3.3V	-3	PQFP	208	COM	5.8K
LFXP6C-4Q208C	142	1.8/2.5/3.3V	-4	PQFP	208	COM	5.8K
LFXP6C-5Q208C	142	1.8/2.5/3.3V	-5	PQFP	208	COM	5.8K
LFXP6C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	5.8K
LFXP6C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	5.8K
LFXP6C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388C	244	1.8/2.5/3.3V	-3	fpBGA	388	COM	9.7K
LFXP10C-4F388C	244	1.8/2.5/3.3V	-4	fpBGA	388	COM	9.7K
LFXP10C-5F388C	244	1.8/2.5/3.3V	-5	fpBGA	388	COM	9.7K
LFXP10C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	9.7K
LFXP10C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	9.7K
LFXP10C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	9.7K

## Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484C	300	1.2V	-3	fpBGA	484	COM	15.5K
LFXP15E-4FN484C	300	1.2V	-4	fpBGA	484	COM	15.5K
LFXP15E-5FN484C	300	1.2V	-5	fpBGA	484	COM	15.5K
LFXP15E-3FN388C	268	1.2V	-3	fpBGA	388	COM	15.5K
LFXP15E-4FN388C	268	1.2V	-4	fpBGA	388	COM	15.5K
LFXP15E-5FN388C	268	1.2V	-5	fpBGA	388	COM	15.5K
LFXP15E-3FN256C	188	1.2V	-3	fpBGA	256	COM	15.5K
LFXP15E-4FN256C	188	1.2V	-4	fpBGA	256	COM	15.5K
LFXP15E-5FN256C	188	1.2V	-5	fpBGA	256	COM	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484C	340	1.2V	-3	fpBGA	484	COM	19.7K
LFXP20E-4FN484C	340	1.2V	-4	fpBGA	484	COM	19.7K
LFXP20E-5FN484C	340	1.2V	-5	fpBGA	484	COM	19.7K
LFXP20E-3FN388C	268	1.2V	-3	fpBGA	388	COM	19.7K
LFXP20E-4FN388C	268	1.2V	-4	fpBGA	388	COM	19.7K
LFXP20E-5FN388C	268	1.2V	-5	fpBGA	388	COM	19.7K
LFXP20E-3FN256C	188	1.2V	-3	fpBGA	256	COM	19.7K
LFXP20E-4FN256C	188	1.2V	-4	fpBGA	256	COM	19.7K
LFXP20E-5FN256C	188	1.2V	-5	fpBGA	256	COM	19.7K

## Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3QN208I	136	1.8/2.5/3.3V	-3	PQFP	208	IND	3.1K
LFXP3C-4QN208I	136	1.8/2.5/3.3V	-4	PQFP	208	IND	3.1K
LFXP3C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	3.1K
LFXP3C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	3.1K
LFXP3C-3TN100I	62	1.8/2.5/3.3V	-3	TQFP	100	IND	3.1K
LFXP3C-4TN100I	62	1.8/2.5/3.3V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	5.8K
LFXP6C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	5.8K
LFXP6C-3QN208I	142	1.8/2.5/3.3V	-3	PQFP	208	IND	5.8K
LFXP6C-4QN208I	142	1.8/2.5/3.3V	-4	PQFP	208	IND	5.8K
LFXP6C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	5.8K
LFXP6C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	5.8K

Date	Version	Section	Change Summary
September 2005 (cont.)	03.0 (cont.)	DC and Switching Characteristics (cont.)	Updated Typical Building Block Function Performance timing numbers.
			Updated External Switching Characteristics timing numbers.
			Updated Internal Timing Parameters.
			Updated LatticeXP Family timing adders.
			Updated LatticeXP "C" Sleep Mode timing numbers.
		Updated JTAG Port Timing numbers.	
		Pinout Information	Added clarification to SLEEPN and TOE description. Clarification of dedicated LVDS outputs.
		Supplemental Information	Updated list of technical notes.
September 2005	03.1	Pinout Information	Power Supply and NC Connections table corrected VCCP1 pin number for 208 PQFP.
December 2005	04.0	Introduction	Moved data sheet from Advance to Final.
		Architecture	Added clarification to Typical I/O Behavior During Power-up section.
		DC and Switching Characteristics	Added clarification to Recommended Operating Conditions.
			Updated timing numbers.
		Pinout Information	Updated Signal Descriptions table. Added clarification to Differential I/O Per Bank. Updated Differential dedicated LVDS output support.
Ordering Information	Added 208 PQFP lead-free package and ordering part numbers.		
February 2006	04.1	Pinout Information	Corrected description of Signal Names VREF1(x) and VREF2(x).
March 2006	04.2	DC and Switching Characteristics	Corrected condition for IIL and IIH.
March 2006	04.3	DC and Switching Characteristics	Added clarification to Recommended Operating Conditions for VCCAUX.
April 2006	04.4	Pinout Information	Removed Bank designator "5" from SLEEPN/TOE ball function.
May 2006	04.5	DC and Switching Characteristics	Added footnote 2 regarding threshold level for PROGRAMN to sysCONFIG Port Timing Specifications table.
June 2006	04.6	DC and Switching Characteristics	Corrected LVDS25E Output Termination Example.
August 2006	04.7	Architecture	Added clarification to Typical I/O Behavior During Power-Up section. Added clarification to Left and Right sysIO Buffer Pair section.
		DC and Switching Characteristics	Changes to LVDS25E Output Termination Example diagram.
December 2006	04.8	Architecture	EBR Asynchronous Reset section added.
February 2007	04.9	Architecture	Updated EBR Asynchronous Reset section.
July 2007	05.0	Introduction	Updated LatticeXP Family Selection Guide table.
		Architecture	Updated Typical I/O Behavior During Power-up text section.
		DC and Switching Characteristics	Updated sysIO Single-Ended DC Electrical Characteristics table. Split out LVCMOS 1.2 by supply voltage.
November 2007	05.1	DC and Switching Characteristics	Added JTAG Port Timing Waveforms diagram.
		Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.